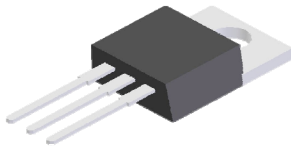


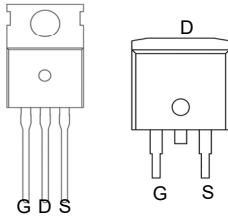
Product Summary

V_{DS}	$R_{DS(ON_MAX)}$		I_{D_MAX}
100 V	3.5 m Ω	@ $V_{GS} = 10V$ TO263-3L	184 A
	3.6 m Ω	@ $V_{GS} = 10V$ TO220-3L	

TO220-3L



Top View

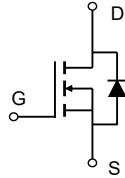


PIN Configuration
(Top View)

TO263-3L



Top View



Schematic Diagram

Features

- Low On-Resistance
- Excellent FoM (figure of merit)
- 100% UIS and R_g tested



Applications

- DC/DC in Telecoms and Industrial
- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit

Mechanical Data

- Green Molding Compound
- Moisture Sensitivity: Level 1 per J-STD-020
- UL Flammability Classification Rating 94V-0

Ordering Information

Orderable Part Number	Package Type	Device Marking	Form	Quantity (pcs)
MX10T03DHSS	TO220-3L	10T03DH	Tube	50
MX10T03DHSS	TO263-3L	10T03DH	13" Tape&Reel	1,000

Maximum Ratings (@ $T_C = 25^\circ\text{C}$, unless otherwise specified.)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	100	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($V_{GS} = 10V$) ⁽¹⁾	I_D	184	A
		130	A
Pulsed Drain Current ⁽²⁾	I_{DM}	736	A
Single Pulse Avalanche Energy ⁽³⁾	E_{AS}	1000	mJ
Single Pulse Avalanche Current ($L = 0.1mH$)	I_{AS}	74	A
Power Dissipation	P_D	254	W
		127	W
Junction & Storage Temperature Range	T_J, T_{STG}	-55 ~ +175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient ⁽⁴⁾	$R_{\theta JA}$	30	35	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case ⁽⁵⁾	$R_{\theta JC}$	0.45	0.59	$^\circ\text{C/W}$

Electrical Characteristics (@ $T_J = 25^\circ\text{C}$, unless otherwise specified.)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit	
Off Characteristics ⁽⁶⁾							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μA	
		T _J = 125°C	-	-	100	μA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA	
On Characteristics ⁽⁶⁾							
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D = 250μA	2.0	3.0	4.0	V	
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 20A	TO263-3L	-	2.9	3.5	mΩ
			TO220-3L	-	3.1	3.6	mΩ
Forward Transconductance	g _{fs}	V _{DS} = 5.0V, I _D = 20A	-	37	-	S	
Diodes Forward Voltage	V _{SD}	I _S = 2.0A, V _{GS} = 0V	-	0.7	1.2	V	
Dynamic Characteristics ⁽⁷⁾							
Input Capacitance	C _{iss}	V _{DS} = 50V, V _{GS} = 0V, f = 1MHz	-	4628	-	pF	
Output Capacitance	C _{oss}		-	1625	-	pF	
Reverse Transfer Capacitance	C _{rss}		-	19	-	pF	
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	-	2.0	-	Ω	
Switching Characteristics ⁽⁷⁾							
Turn-On DelayTime	t _{d(on)}	V _{GS} = 10V, V _{DS} = 50V I _D = 20A, R _{GEN} = 3.0Ω	-	12	-	ns	
Rise Time	t _r		-	26	-	ns	
Turn-Off DelayTime	t _{d(off)}		-	38	-	ns	
Fall Time	t _f		-	31	-	ns	
Gate Charge Characteristics ⁽⁷⁾							
Total Gate Charge (V _{GS} = 10V)	Q _g	V _{DS} = 50V, I _D = 20A V _{GS} = 10V	-	61	-	nC	
Total Gate Charge (V _{GS} = 6.0V)	Q _g		-	38	-	nC	
Gate-Source Charge	Q _{gs}		-	20	-	nC	
Gate-Drain Charge	Q _{gd}		-	8.7	-	nC	
Gate Plateau Voltage	V _{plateau}		-	4.4	-	V	
Drain-Source Diode Characteristics ⁽⁷⁾							
Body Diode Reverse Recovery Time	t _{rr}	I _F = 20A, dI/dt = 100A/μs,	-	77	-	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	T _J = 25°C	-	189	-	nC	
Diode Forward Current	I _S	T _C = 25°C	-	-	184	A	

Notes:

1. This current is chip limited, which is calculated based on R_{thjc} .
2. This current is calculated on single pulse with 10 μs Pulse & Duty Cycle = 1%.
3. Defined by design, not subject to production test, E_{AS} condition: $T_J=25^\circ\text{C}, V_{DD}=50V, V_{GS}=10V, L=1.0\text{mH}$.
4. Device mounted on FR-4 substrate PC board with 2oz copper in 1inch square cooling area.
5. Thermal resistance from junction to soldering point (on the exposed drain pad).
6. Short duration pulse test used to minimize self-heating effect.
7. Defined by design, not subject to production.

Typical Electrical and Thermal Characteristics

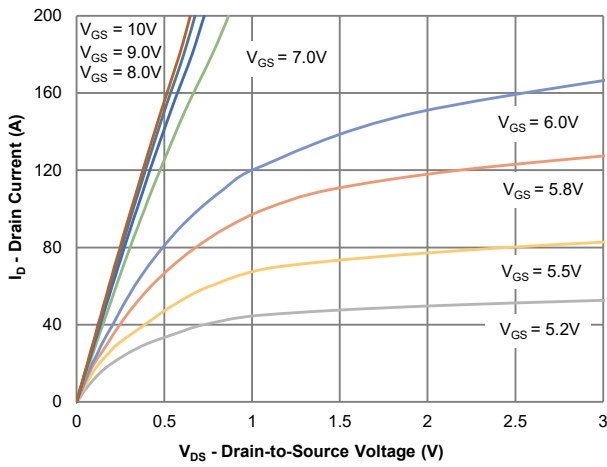


Figure 1: Output Characteristics

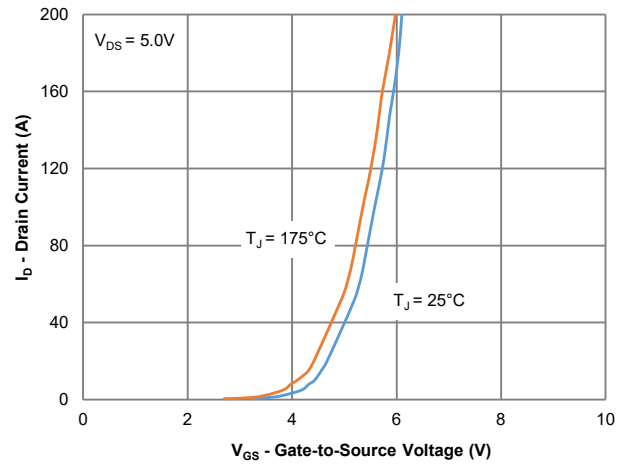


Figure 2: Transfer Characteristics

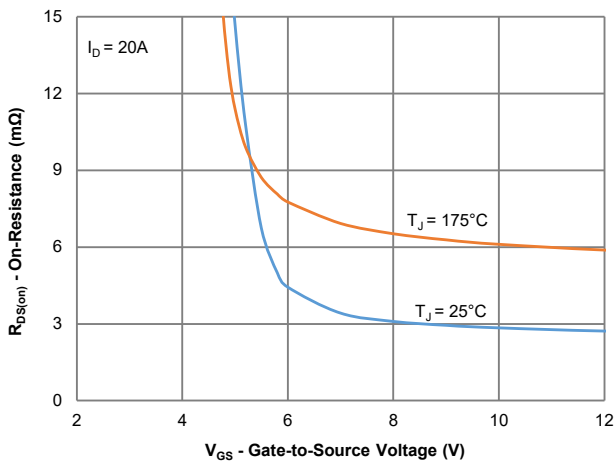


Figure 3: On-Resistance vs. Gate-Source Voltage

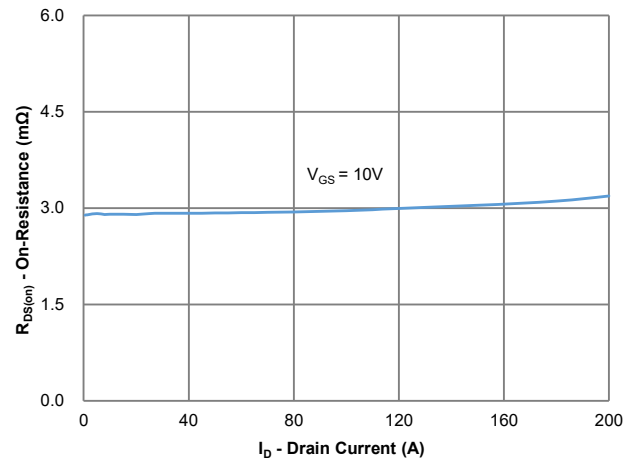


Figure 4: On-Resistance vs. Gate-Source Voltage

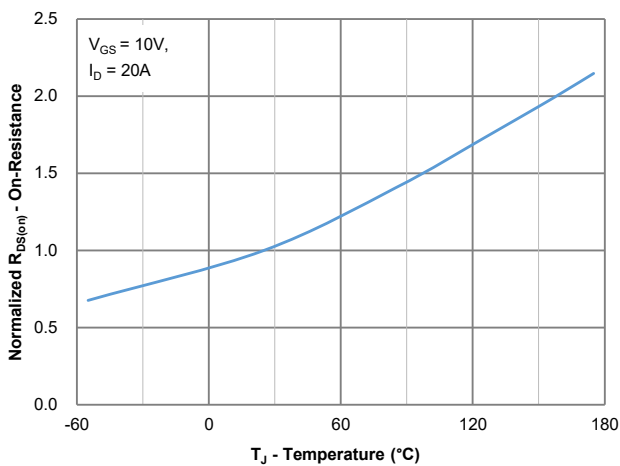


Figure 5: On-Resistance vs. Junction Temperature

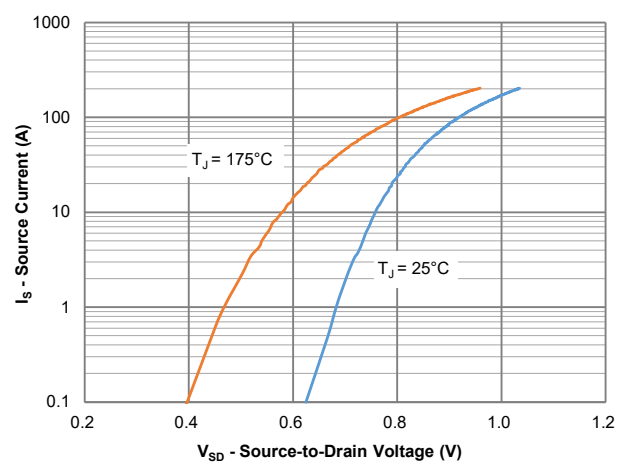


Figure 6: Source-Drain Diode Forward Voltage

Typical Electrical and Thermal Characteristics

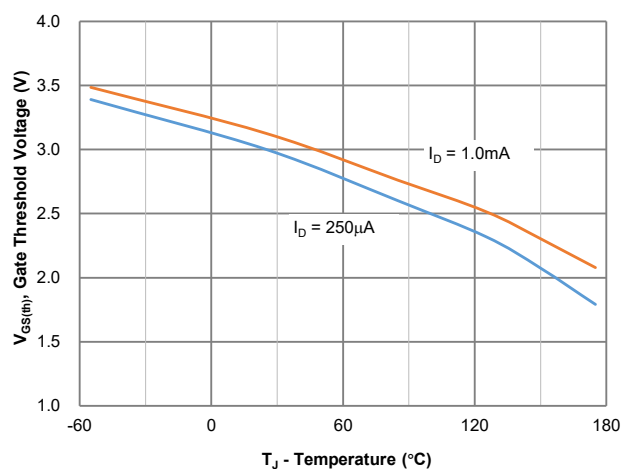


Figure 7: Gate Threshold Variation vs. Junction Temperature

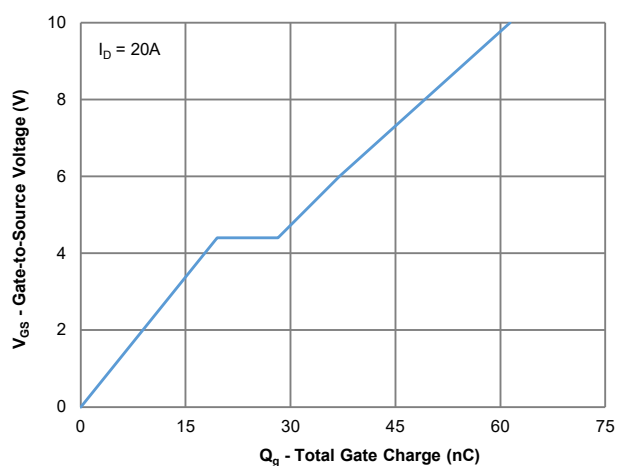


Figure 8: Gate Charge Characteristics

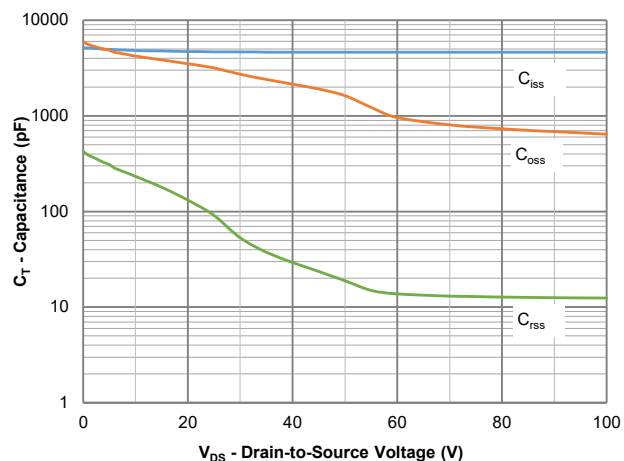


Figure 9: Capacitance Characteristics

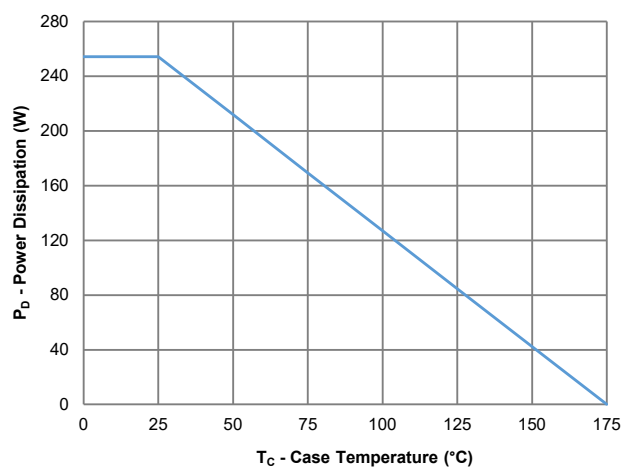


Figure 10: Power Derating

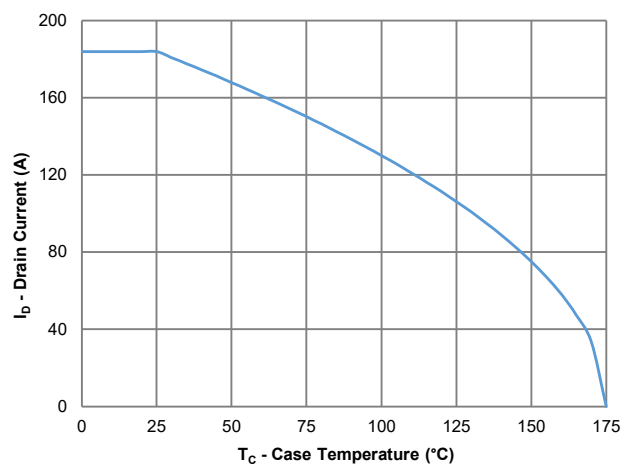


Figure 11: Current Derating

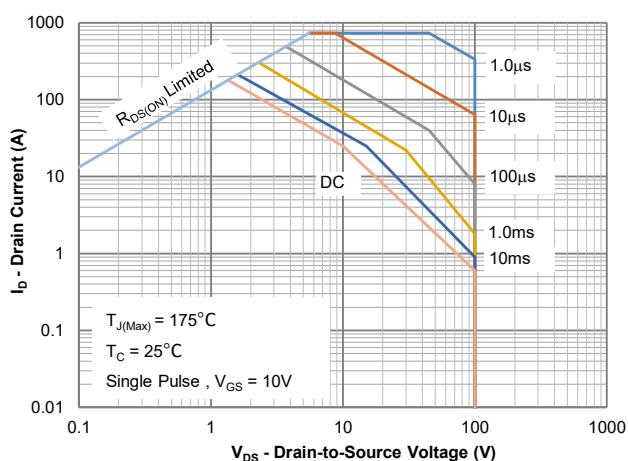


Figure 12: Safe Operating Area

Typical Electrical and Thermal Characteristics

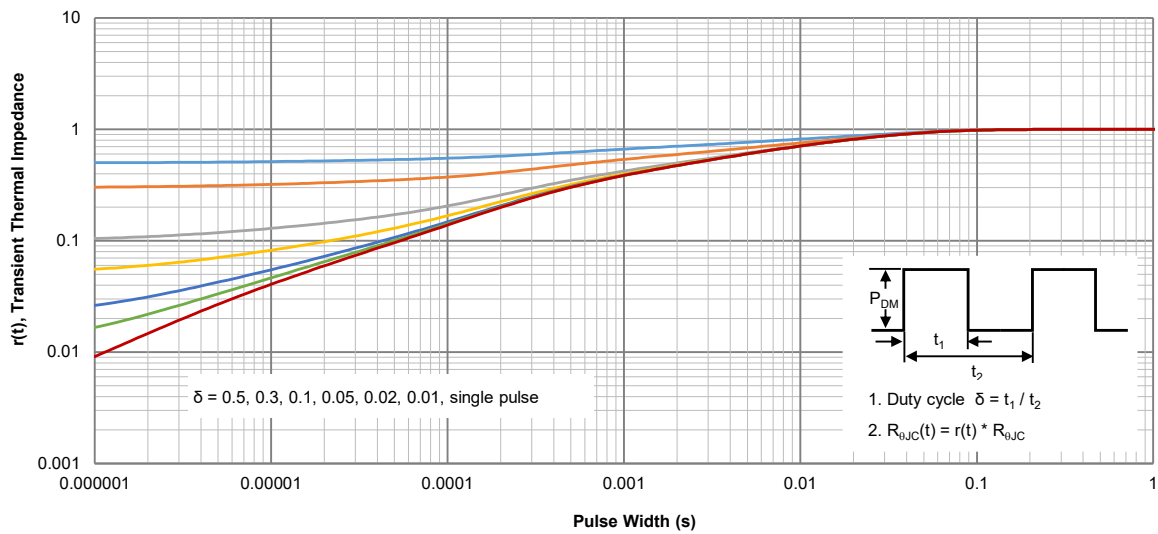
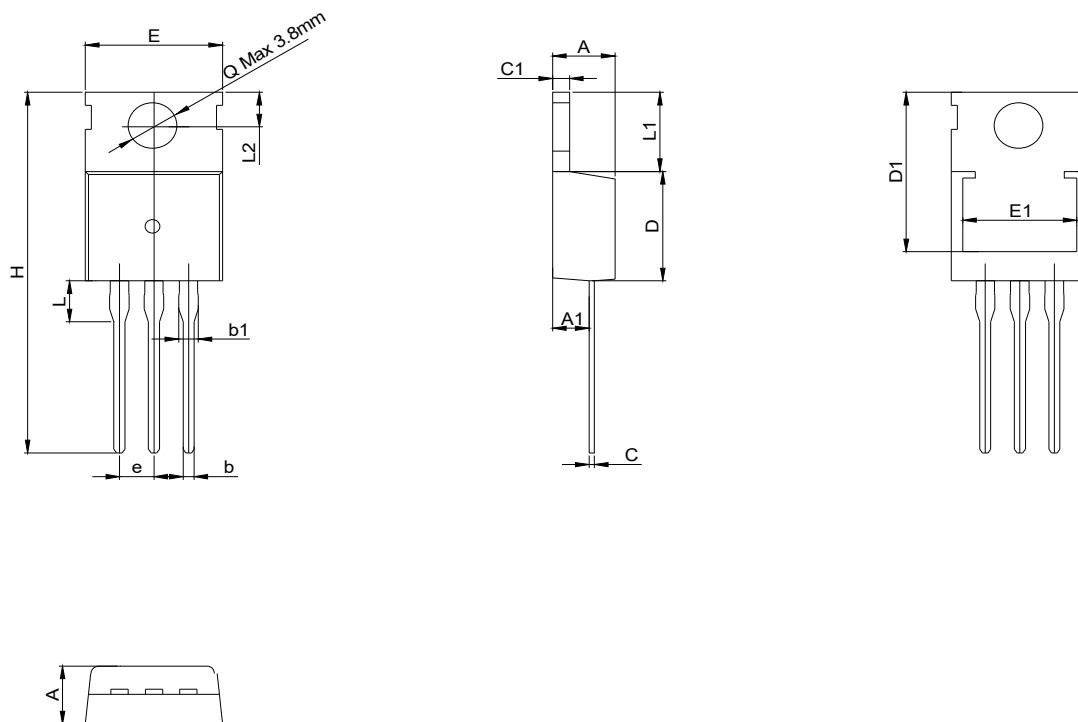


Figure 13: Normalized Maximum Transient Thermal Impedance

TO220-3L Package Outline

Package Outline



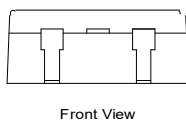
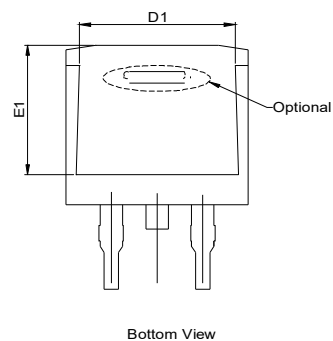
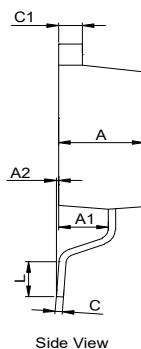
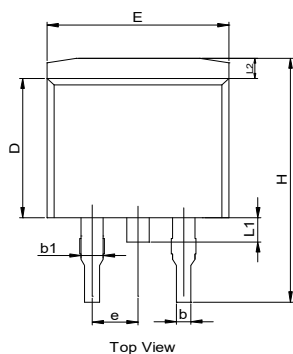
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMNESIONS IN MILLIMETER (ANNGLE IN DEGREE).
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.35	4.50	4.70
A1	2.20	2.30	3.00
b	0.70	0.80	0.95
b1	1.10	1.30	1.50
C	0.45	0.50	0.60
C1	1.23	1.30	1.40
H	28.00	28.80	29.80
D	8.80	9.21	9.90
D1	12.80	13.20	13.60
E	9.70	10.00	10.50
E1	7.40	8.00	8.60
L	--	--	3.80
L1	6.25	6.50	6.90
L2	2.40	2.90	3.05
e	2.54 BSC		

TO263-3L Package Outline

Package Outline



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS IN MILLIMETER (ANGLE IN DEGREE).
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.20	4.50	4.70
A1	2.30	--	2.85
A2	0.00	0.10	0.25
b	0.70	0.80	0.95
b1	1.15	1.30	1.70
C	0.30	0.50	0.60
C1	1.15	1.30	1.42
H	14.00	15.20	15.88
D	8.50	9.20	9.60
D1	6.80	7.75	8.00
E	9.78	10.00	10.36
E1	6.80	7.95	8.10
L	1.50	--	2.80
L1	--	--	1.75
L2	1.35 REF		
e	--	2.54	--

Recommended Soldering Footprint :

